

IN THE CLAIMS:

Claims 1, 2, 4-6, 8-11, 13, 14, 17, 19, and 25-27 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

Listing of Claims:

1.-2. (Cancelled)

3. (Previously presented) A transfer molding apparatus comprising:
first and second members configured to be assembled with one another;
at least one encapsulant restraining cavity formed in at least one of the first and second members,
the at least one cavity extending longitudinally in a non-horizontal orientation;
at least one gate at a lower portion of the at least one cavity;
at least one vent at an upper portion of the at least one cavity; and
wherein the at least one cavity includes at least one surface with recesses formed therein, each of
the recesses having a boundary wall that is sized and configured to substantially
conformally receive a portion of one of a plurality of conductive structures protruding
from a substrate positionable in the at least one cavity.

4.-6. (Cancelled)

7. (Previously presented) A transfer molding apparatus comprising:
first and second members to be assembled with one another;
at least one encapsulant restraining cavity formed in at least one of the first and second members,
the at least one cavity extending longitudinally in a substantially vertical orientation;
at least one gate at a lower portion of the at least one cavity;
at least one vent at an upper portion of the at least one cavity; and
wherein the at least one cavity includes at least one surface with recesses formed therein, each of
the recesses defined by a boundary wall that is sized and configured to substantially
conformally receive a portion of one of a plurality of conductive structures protruding
from a substrate positionable in the at least one cavity.

8.-11. (Cancelled)

12. (Previously presented) A transfer molding apparatus for molding a substrate in a
substantially vertical orientation, the apparatus comprising:
a first member and a second member configured to be assembled with one another, each of the
first member and the second member having an inside surface and an outside surface;
multiple encapsulant restraining cavities each formed in the inside surface of at least one of the
first member and the second member, each of the multiple cavities sized and configured
for the substrate to be disposed therein, the multiple cavities extending longitudinally in a
non-horizontal orientation;
at least one gate formed in any one of the first member and the second member extending from a
lower portion of each of the multiple cavities;
at least one vent formed in any one of the first member and the second member extending from
an upper portion of each of the multiple cavities; and
wherein at least one of the multiple cavities includes recesses formed in the inside surface on the
at least one of the first member and the second member, each of the recesses defined by a
boundary wall that is sized and configured to substantially conformally receive a portion

of one of a plurality of conductive structures protruding from the substrate positionable in the at least one of the multiple cavities.

13.-14. (Cancelled)

15. (Previously presented) The transfer molding apparatus of claim 12, wherein the multiple cavities are configured and longitudinally oriented to provide a substantially vertical flow for encapsulation of the substrate positionable in the multiple cavities.

16. (Previously presented) The apparatus according to claim 3, wherein the at least one cavity comprises a substantially vertically oriented cavity.

17. (Cancelled)

18. (Previously presented) The apparatus according to claim 7, wherein the at least one cavity is configured to provide a substantially vertical flow for encapsulation of a substrate positionable in the at least one cavity.

19. (Cancelled)

20. (Previously presented) The transfer molding apparatus of claim 12, wherein each of the multiple cavities comprises a substantially vertically oriented cavity.

21. (Previously presented) The transfer molding apparatus of claim 12, wherein each of the multiple cavities includes a longitudinal length substantially oriented along a substantially vertical orientation.

22. (Previously presented) The transfer molding apparatus of claim 3, wherein the plurality of conductive structures comprise pillars or columns.

23. (Previously presented) The transfer molding apparatus of claim 7, wherein the plurality of conductive structures comprise pillars or columns.

24. (Previously presented) The transfer molding apparatus of claim 12, wherein the plurality of conductive structures comprise pillars or columns.

25.-27. (Cancelled)

IN THE DRAWINGS:

The attached sheets of drawings include changes to FIGS. 1, 2, 3, 5, 6, 7, and 8. These sheets replace the original sheets including FIGS. 1, 2, 3, 5, 6, 7, and 8.

Specifically, FIGS. 1-3 have been revised to add the designation --(PRIOR ART)-- below each figure's label; FIG. 5 has been revised to change the reference numerals "6'," "14'," "16'," and "18'" to --6--, --14--, --16-- and --18--, respectively; FIG. 6 has been revised to change the reference numerals "4'," "5'," "6'," "10'," "12'," "14'," "16'," and "20'" to --4--, --5--, --6--, --10--, --12--, --14--, --16-- and --20--, respectively; FIG. 7 has been revised to change the reference numerals "4'", "6'", "12'", "16'", and "20'" to --4--, --6--, --12--, --16-- and --20--, respectively; and FIG. 8 has been revised to change the reference numeral "106" to --6--, "112" to --12-- and "116" to --16--. No new matter has been added.